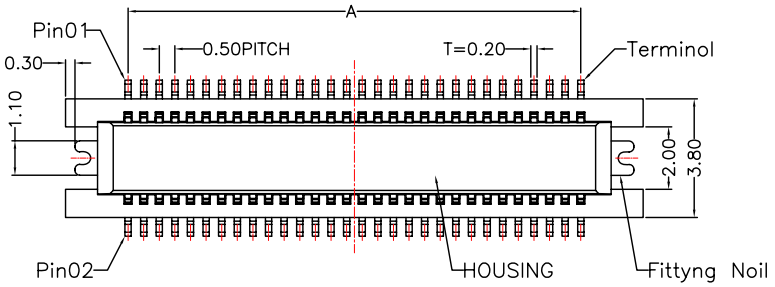
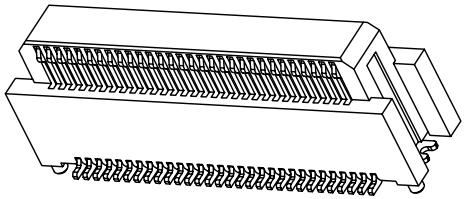
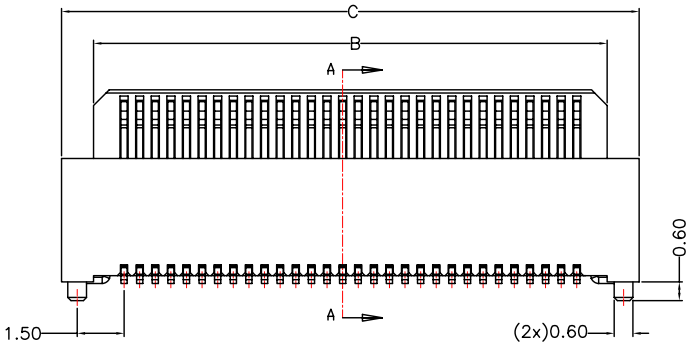
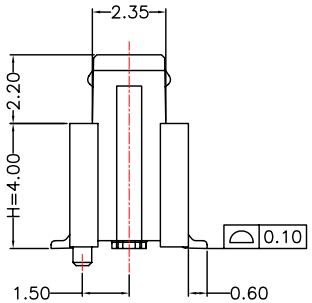
REV	ECN	DESCRIPTION	MDF'D	DATE
1.0	/	新发行	Fan Z.J.	2023/11/22

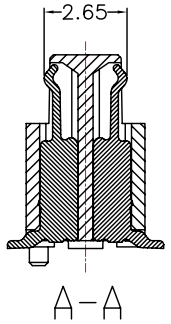
CKT	Dim A	Dim B	Dim C
16	3.5	5.5	7.5
20	4.5	6.5	8.5
30	7.0	9.0	11.0
40	9.5	11.5	13.5
50	12.0	15.0	16.0
60	14.5	16.5	18.5
70	17.0	19.0	21.0
80	19.5	21.5	23.5
100	24.5	26.5	28.5
120	29.5	31.5	33.5

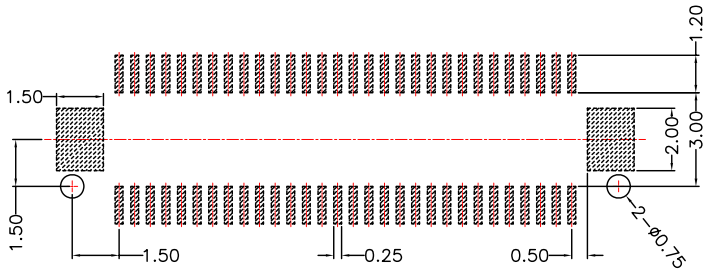












NECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

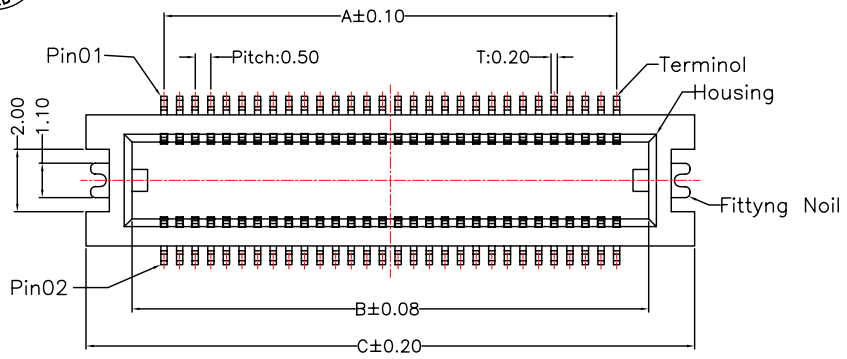
8BT M 009 A 060 XX 40 1 P

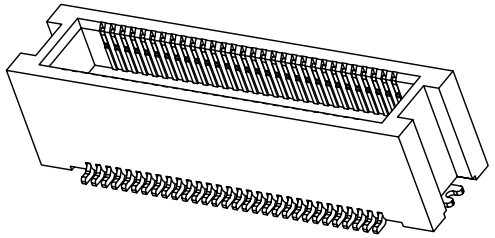
- P:有柱 F：无柱
- 产品高：例1.0对应10
- 电镀码：E0: Gold Flash 接触区镀金（半金锡）
  E1: 1u" 接触区镀金（半金锡）
  E5: 15u"接触区镀金（半金锡）
  E0: 30u"接触区镀金（半金锡）
  L4: 全锡150u"
- PIN码：020: 2x10Pin
  060: 2x30Pin.....

NOTES:
1.MATERIAL:
1.1 HOUSING:THERMOPLASTIC,HIGH TEMP.,UL94V-0;
1.2 CONTACTS: COPPER ALLOY.
1.3 FITTING NAIL: COPPER ALLOY.
2. FINISH:
2.1 CONTACT:
50u" MIN. NICKEL UNDERPLATING COVER ALL
E1: GOLD FLASH PLANTING(1~3u") OVER ALL
E5: 15u" GOLD PLATING ON CONTACT AREA
E7: 30u" GOLD PLATING ON CONTACT AREA
L4: 100~200u" MIATT TIN PLATING OVER ALL
2.2 TITTING NAIL:
3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.

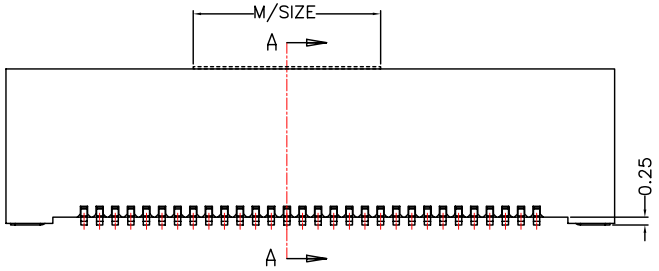
.X ±0.5	.XX° ±0.5°	东莞市文章济美电子有限公司
.XX ±0.3	.XX° ±0.5°	DONGGUAN ARTICLE JIMEI ELECTRONICS CO., LED.
.XXX ±0.2	.XXX° ±0.2°	Part Name: 0.5mm BTB Rept. SMT S/T D/R TYPE-公头 / Approved:
SCALE 1:1	UNIT mm	Part No.: 8BT M 009 A 060 XX 40 1 P / Checked:
PAGE: 1/1	REV: 1.0	Title: / Material: / Drawn: Fan Z.J.
		Drawing No.: G8BTC0015 / Mode NO.: / Date: 2023-11-22

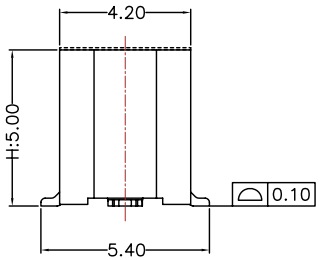
REV	ECN	DESCRIPTION	MDF'D	DATE
1.0	/	新发行	fan Z.J.	2023-07-08

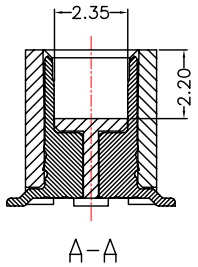


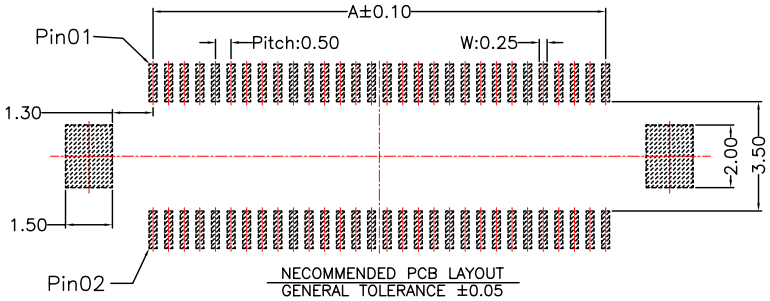


CKT	Dim A	Dim B	Dim C	M(size)
16	3.5	5.5	8.5	6.00
20	4.5	6.5	9.5	6.00
30	7.0	9.0	12.0	6.00
40	9.5	11.5	14.5	15.0
50	12.0	15.0	17.0	15.0
60	14.5	16.5	19.5	15.0
70	17.0	19.0	22.0	15.0
80	19.5	21.5	24.5	15.0
100	24.5	26.5	29.5	15.0
120	29.5	31.5	34.5	15.0
160	39.5	41.5	44.5	15.0









8BT F 009 A 060 XX 50 1 F

- P:有柱 F：无柱
- 产品高：例1.0对应10
- 电镀码：E0：Gold Flash 接触区镀金（半金锡）
  E5：15u"接触区镀金（半金锡）
  E0：30u"接触区镀金（半金锡）
  L4：全锡150u"
- PIN码：020：2x10Pin
  060：2x30Pin.....

NOTES:
1.MATERIAL:
1.1 HOUSING:THERMOPLASTIC,HIGH TEMP.,UL94V-0;
1.2 CONTACTS: COPPER ALLOY.
1.3 FITTING NAIL: COPPER ALLOY.
2. FINISH:
2.1 CONTACT:
50u" MIN. NICKEL UNDERPLATING COVER ALL
E1: GOLD FLASH PLANTING(1~3u") OVER ALL
E5: 15u" GOLD PLATING ON CONTACT AREA
E7: 30u" GOLD PLATING ON CONTACT AREA
L4: 100~200u" MIATT TIN PLATING OVER ALL
2.2 TITTING NAIL:
3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.

.X ±0.20	.X° ±1.0°	东莞市文章济美电子有限公司	
.XX ±0.10	.XX° ±0.5°	DONGGUAN ARTICLE JIMEI ELECTRONICS CO., LED.	
.XXX ±0.05	.XXX° ±0.2°	Part Name: 0.5mm BTB Rept. SMT S/T D/R TYPE-母座	Approved:
	SCALE 1:1 / UNIT mm	Part No.: 8BT F 009 A 060 XX 50 1 F	Checked:
PAGE: 1/1	REV: 1.0	Title: / Material:	Drawn: Fan Z.J.
		Drawing No.:G8BTC0016 / Mode NO.:	Date: 2022-06-28